| ASSOCIATION CONNECTING<br>ELECTRONICS INDUSTRIES® International and Par | PC. Bannockl  | burn, Illinois, A    | ll rights reserved untions. | under both              | This docume<br>level parts, t | ent is a declaration<br>he declaration en | on of the su            | bstances v<br>all lower | vithin the manufactu<br>level materials for v | rer listed<br>which the 1       | item. Note: i<br>nanufacture    | if the item is an as<br>r has engineering | sembly with low responsibility. |  |
|---|---------------|----------------------|-----------------------------|-------------------------|-------------------------------|---|-------------------------|-------------------------|---|---------------------------------|---------------------------------|---|---------------------------------|--|
|   |               |                      |                             | Form Type<br>Distribute |                               |   |                         |                         | ials and Mfg Information                      |                                 |                                 |   |                                 |  |
| upplier Information   |               |                      |                             |                         |                               |   |                         |                         |   |                                 |                                 |   |                                 |  |
| Company name* Con   |               |                      | Company unique ID           |                         |                               | Unique ID Authority                       |                         |                         |   | Respon                          | Response Date*                  |   |                                 |  |
| nsemi   |               |                      |                             |                         |                               |   |                         |                         |   | 2023-06-08                      |                                 |   |                                 |  |
| ontact Name Title - Contact   |               |                      | ;t                          |                         |                               | Phone - Contact*                          |                         |                         |   | Email -                         | Email - Contact*                |   |                                 |  |
| Product-Env-Stewards Product En   |               |                      | et Enviro Compliance        |                         |                               | NA  |                         |                         |   | Product-Env-Stewards@onsemi.com |                                 |   |                                 |  |
| Authorized Representative* Title - Repr                                 |               |                      | epresentative               |                         |                               | Phone - Representative*                   |                         |                         |   | Email - Representative*         |                                 |   |                                 |  |
| Product-Env-Stewards Produc   |               |                      | oduct Enviro Compliance     |                         |                               | NA  |                         |                         |   | Produ                           | Product-Env-Stewards@onsemi.com |   |                                 |  |
| Requester Item Number   | Mfr Iten      | n Number             | Mfr Item Name               |                         |                               | Effective Date                            | Version                 | М                       | Manufacturing Site                            |                                 | Weight*                         | UOM                                       | Unit Type                       |  |
|   | MOC30         | OC3082SM 6PW ZC TRIA |                             | C SMD                   |                               | 2023-06-08                                |                         | TI                      | ТНН   |                                 | 464.903                         | mg  | Each                            |  |
| Ianufacturing Proccess Informa  | tion          |                      | ·                           |                         |                               | ·   |                         | ·                       |   |                                 |                                 | ·   |                                 |  |
| Terminal Plating / Grid Array M   | aterial 7     | Ferminal Base A      | Alloy J-STD-020 MSL Rati    |                         | L Rating                      | Peak Proce                                | rocess Body Temperature |                         | e Max Time at Peak                            | . Tempera                       | ture Num                        | ber of Reflow Cyc                         | les                             |  |
| Matte Tin (Sn) - annealed CU A  |               | CU Alloy             | 1                           |                         |                               | <b>260</b> C                              |                         | С                       | 30 seco                                       |                                 | seconds 3                       |   |                                 |  |
| omments   |               |                      |                             |                         |                               |   |                         |                         |   |                                 |                                 |   |                                 |  |
| vel 1 - maximum time at peak temperatu                                  | ire during so | ldering is 10-3      | 0 seconds                   |                         |                               |   |                         |                         |   |                                 |                                 |   |                                 |  |
| or more information regarding material                                  | composition   | please refer to      | page 3                      |                         |                               |   |                         |                         |   |                                 |                                 |   |                                 |  |

| RoHS Material Composition Declaration  |  |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |
|--|--|--|---|---|---|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | oHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl hthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>y others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the   | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and co<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa  | on above   | Supplier Acceptance   | * Accepted                                      |   |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per   | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |  |   |   |   |  |  |  |  |  |
| Declaration Signature  |  |  |   |   |   |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester  | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska  | Le   |   |   |   |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight  | Unit of Measure | Level    | Substance                               | CAS        | Exempt | Weight  | Unit of Measure |
|----------------------|---------|-----------------|----------|---|------------|--------|---------|-----------------|
| Coupling Gel         | 0.4     | mg              | Supplier | Dimethyl Cyclosiloxanes                 | 69430-24-6 |        | 0.04    | mg              |
|                      |         |                 | Supplier | Trimethoxy(methyl)silane (C4H12O3Si)    | 1185-55-3  |        | 0.36    | mg              |
| Die                  | 5.13    | mg              | Supplier | Silicon (Si)                            | 7440-21-3  |        | 5.13    | mg              |
| Die Attach           | 0.3     | mg              | Supplier | Silver (Ag)                             | 7440-22-4  |        | 0.225   | mg              |
|                      |         |                 | Supplier | Phenolic Resin-2                        | 54208-63-8 |        | 0.075   | mg              |
| Lead Frame           | 101.703 | mg              | Supplier | Silver (Ag)                             | 7440-22-4  |        | 0.407   | mg              |
|                      |         |                 | Supplier | Zinc (Zn)                               | 7440-66-6  |        | 0.203   | mg              |
|                      |         |                 | Supplier | Iron (Fe)                               | 7439-89-6  |        | 2.64    | mg              |
|                      |         |                 | Supplier | Copper (Cu)                             | 7440-50-8  |        | 98.3    | mg              |
|                      |         |                 | Supplier | Phosphorus (P)                          | 7723-14-0  |        | 0.153   | mg              |
| Mold Compound-White  | 327.22  | mg              | Supplier | Titanium Dioxide (TiO2)                 | 13463-67-7 |        | 81.805  | mg              |
|                      |         |                 | В        | Brominated Bisphenol A Diglycidyl Ether | 40039-93-8 |        | 9.8166  | mg              |
|                      |         |                 | Supplier | Ortho Cresol Novolac Resin              | 29690-82-2 |        | 44.1747 | mg              |
|                      |         |                 | В        | Antimony Trioxide (Sb2O3)               | 1309-64-4  |        | 9.8166  | mg              |
|                      |         |                 | Supplier | Fused Silica (SiO2)                     | 60676-86-0 |        | 163.61  | mg              |
|                      |         |                 | Supplier | Phenolic Resin (Novolac)                | 9003-35-4  |        | 17.9971 | mg              |
| Plating              | 28.5    | mg              | Supplier | Tin (Sn)                                | 7440-31-5  |        | 28.5    | mg              |
| Wire Bond - Au       | 1.65    | mg              | Supplier | Gold (Au)                               | 7440-57-5  |        | 1.65    | mg              |